

# **Product Specification**

Product Name:	Golden Finger Signal Socket				
Product Model:	C0304050FG15SBHP1163				
Reed Name:	Golden finger terminal-20~26AWG				
	-12.27mm-3A-/-ROHS				

The product completely meet ROHS requirement.

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	Product Specification

# I. Edition Management

Edition	Made(revised)	Made(revised)by	Checked	Approved	Date	Remarks

## II. Product Specification

#### 1. Scope

The Specification applies to the golden finger signal socket of PCB with thickness 1.6mm.

#### 2. Reference Standard

MIL-STD-202 Test Method: apply to electronics and electronic parts

MIL-STD-1344A Test Method: apply to electronic connectors

#### 3. Detailed Requirement

#### 3.1 Design & Manufacture

Product design, manufacture, physical dimensions must meet the requirement of drawing.

#### 3.2 Materials & Plate Coat

a) Reed: phosphor bronze, C5210, HV190-210, other details referred to attached BOM list or assembled drawings

#### 3.3 Main specification

a) Rating Voltage: 380V/DC

b) Rating Current: 3A/pin

c) Work Temperature: -55 -105

d) Storage Temperature: -55 -105 , Humidity: 15-85%RH

#### 3.4 Appearance Requirement

Metal Parts : Surface clean and polishing , color of plate coat without obvious difference , no scratch, no rusty erosion, no skin rasping.

#### 4. Electrical Performance

Item	Description	Test Method & Condition	Standard
4.1	Contact	Refer to MIL-STD-1344A standard of 3004.1;Use	Origin Value : 20 mΩ(Max)
	Resistance	low level ( Max 20mv , Min100mA )	After test value : 30mΩ(Max)

#### 5. Mechanical Performance

Item	Description	Test Method & Condition	Standard
5.1	Reed retention	Refer to MIL-STD-1344A standard 2007.1 ,	500gf/PIN(MIN)
	force	withdraw reed parts from socket under the speed	
		of 25mm/s	

5.2	Insert-Withdraw	Use the matching PCB board to insert and	After500CYCinsert parts of reed
	lifecycle	withdraw it with 500times;pre-insert about5 times	without distortion , shell without
		before test。Speed:insert-withdraw about15 times	damage , Contact Resistance≤30
		/minute	mΩ , Insert-Withdraw force lose
			less than3% ,
			_
5.3	Insert-Withdraw	Refer to MIL-STD-1344A standard , Test the	Insert-Withdraw force≤3kg
	force between	insert-withdraw force of signal socket used the	
	PCB board and	matching PCB board	
	signal socket		

## 6. Environment Ageing Test

Item	Description	Test Condition	Standard
6.1	Heat	Unassembled connectors referred to	After test , the appearance of
	humidity	MIL-STD-1344AStandard,Model1,Condition	connector without distortion ,
	Test	B, Method 1002.2 : Temperature :	cracks , dimensions without
		30°C+2°C , Humidity : 95±2% ( RH ) ,	variation ,Contact Resistance less
		Continuous Time : Conduct withstand	than $30m\Omega$ , Insulate Resistance
		voltage test immediately after 48hrs under	over $5000M\Omega$ ,
		707V DC .	
6.2	High-Low	Test of connectors must refer to the below	
	Temperature	methods:-40°C ( 30 minutes ) ~ +70°C ( 30	
	Shock Test	minutes), Recycle over 10 times	
6.3	Salt-Spray	Test of connectors must refer to	Contact Resistance less than
	Test	GB/T2423.17 : Temperature : 35±2°C ,	$50 \text{m}\Omega$ , Insulate Resistance over
		Concentration of Salt water : 5±1% ,	$5000$ M $\Omega$ , Plate Gold area permit
		Continuous time: 72H	≤5% square erosion
6.4	High	Test must refer to MIL-STD-1344A,Method	After test, shell without damage ,
	Temperature	1005.1, Testing under70°C with 96hrs	Contact Resistance≤30 mΩ
	Test		
	Low	Testing under-40°C with 96 hrs , and then	
	Temperature	leave it in natural environment with 1hr,	
	test	and then conduct test again	

## 7. Reliability

7.1	Shake	Frequency 10 ~ 55-10HZ ( Feature Level	Instant Stop < 1µs , after test , structure
	test	2),Swing: 1.52mm through axis X/Y/Z,	without looseness , solder-loose , loose
		under accelerate speed of 50m/s2 with	contact , mechanical damage , Contact
		30minutes	Resistance ≤30mΩ ,
7.2	Shock	Pulse: Half-sinusoid; Accelerate: 490m/s2,	
	test	X/Y/Z six views 3 times each	
		Cycle: 11ms	

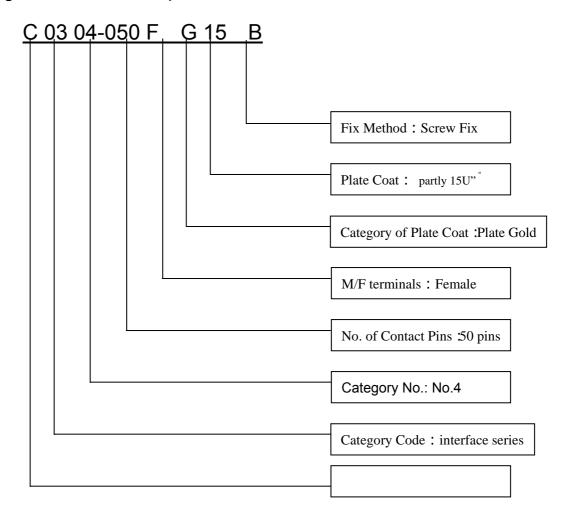
# **III.** Test Sequence

						Test Gro	up			
Te	est Description	Α	В	С	D	Е	F	G	Н	I
					Te	st Seque	ence	L		
1	Product Test	1,9	1,9	1,9	1,9	1,9	1,9	1,9	1,9	1,9
2	Contact Resistance	4 , 8	2,6	2,6	2,6	2,6	2,6	2,6	2,6	2,6
3	Withstand Volt		4,8	4 , 8	4 , 8	4,8	4,8	4,8	4,8	4,8
4	Insulate Resistance		3,7	3,7	3,7	3,7	3,7	3,7	3,7	3,7
8	Heat & Humidity Test		5							
9	High-Low Temperature shock test			5						
10	High-Low Test				5					
11	Salt-Spray Test					5				
14	Shake Test								5	
15	Shock Test									5

Attached: All test excluding special requirements listed in above sheets are conducted under normal room temperature; choose test samples randomly from production line; 5 pcs sample out of each test group; can't repeatedly use the tested sample after test.

# IV. Product Naming Method & Material BOM Sheet

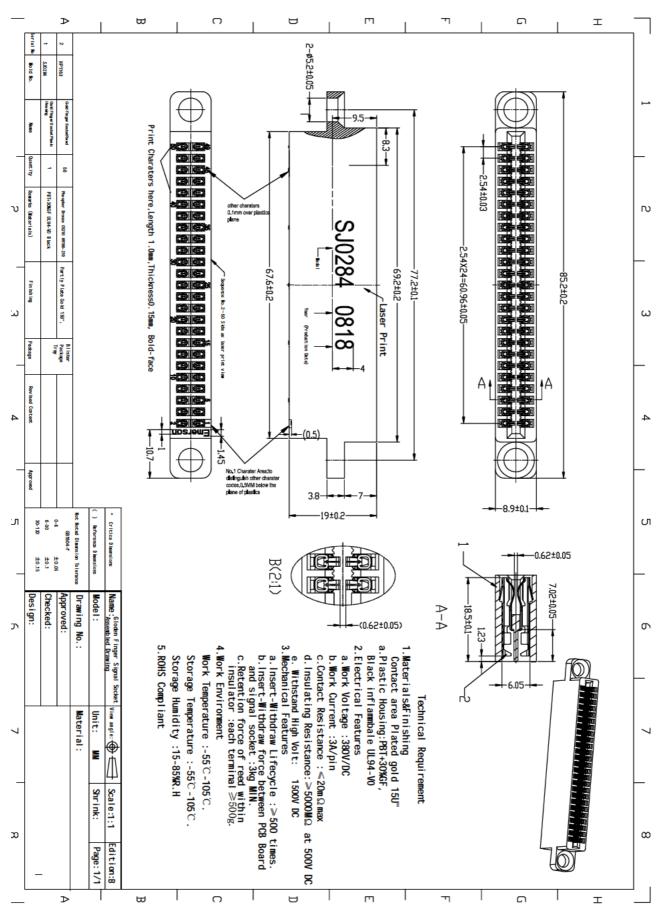
1. Naming Method: (Whole parts of connector)

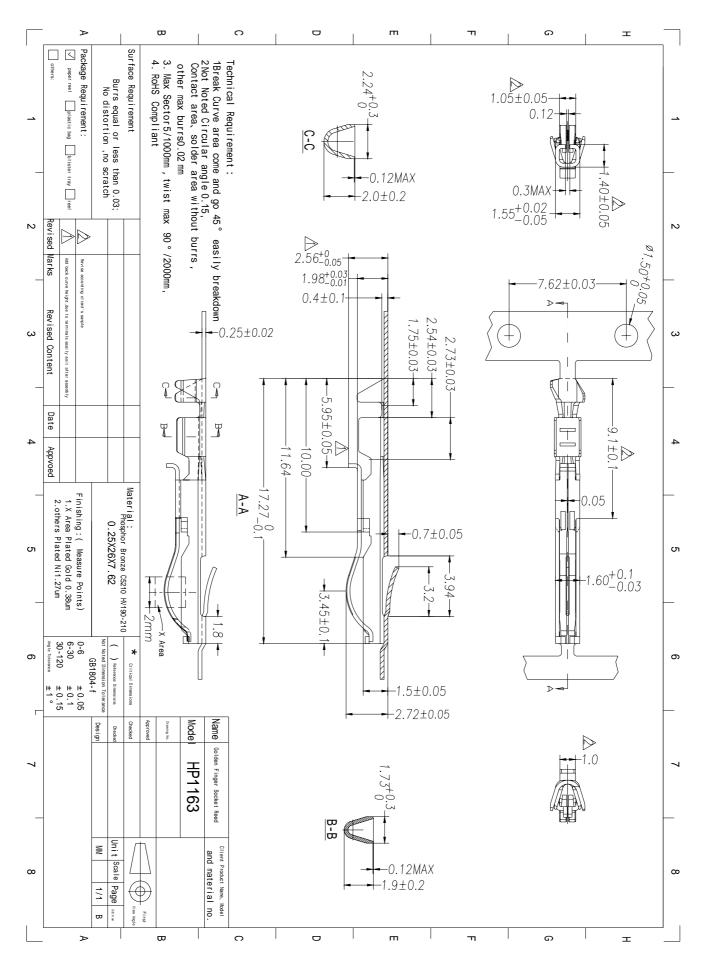


#### 2. Assembled Parts Model& Materials BOM Sheet

Parts Name	Model	Material Name	Brand Name	Quantity	UL
Reed	HP1163	Phosphor Copper	C5210	50	

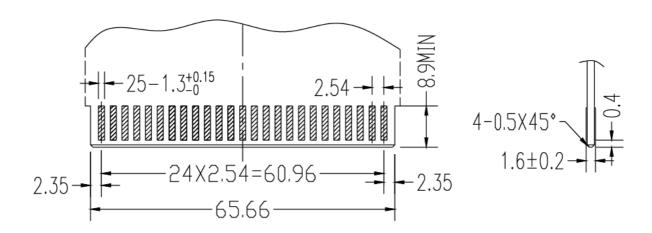
## V. Product Drawing





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### VI. PCB Board Outline Dimensions



Note: 1. PCB Board Thickness:  $1.6\pm0.20$ 

2 Not noted tolerance  $\pm 0.15$ 

## VII. Edition Revised Explanation

Edition B : Mainly Revised Contents as below:

- 1. Assembled Part HP1163 Golden Ring Signal Socket Reed: Postion"1", increase Curve Height.
- 2. Assembled HP1163 Golden Ring Signal Socket Reed: Position "2", revised according to client sample.